Freescale Semiconductor Inc

PART INFORMATION	
Mfg Item Number	FXLN8361QR1
Mfg Item Name	QFN-COL 12 3*3*0.95 P.65

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-08-31
Response Document ID	00DJK50008S349A1.8
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
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Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	No
HalogenFree	No
Plating Indicator	e4
EU RoHS Exemption(s)	7c-I

MANUFACTURING	
Mfg Item Number	FXLN8361QR1
Mfg Item Name	QFN-COL 12 3*3*0.95 P.65
Version	ALL
Weight	0.023800
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	1
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Bonding Wire	0.0001						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0001	g	1000000	100		4201	0.4201
Silicon Semiconductor Die	0.0003						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000006	g	20000	2		252	0.0252
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.000294	g	980000	98		12352	1.2352
Die Encapsulant	0.0133						g					
Die Encapsulant		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00000008	g	6	0.0006		3	0.0003
Die Encapsulant		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00013353	g	10040	1.004		5610	0.561
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00100149	g	75300	7.53		42079	4.2079
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00004006	g	3012	0.3012		1683	0.1683
Die Encapsulant		Lead/Lead Compounds	Lead	7439-92-1		0.00000021	g	16	0.0016		8	0.0008
Die Encapsulant		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.00004006	g	3012	0.3012		1683	0.1683
Die Encapsulant		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.00073441	g	55219	5.5219		30857	3.0857
Die Encapsulant		Glass	Silica, vitreous	60676-86-0		0.01135016	g	853395	85.3395		476907	47.6907
Copper Lead Frame	0.0068						g					
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.00634179	g	932615	93.2615		266461	26.6461
Copper Lead Frame		Metals	Gold, metal	7440-57-5		0	g	0	0		0	0
Copper Lead Frame		Solvents, additives, and other materials	Silicon	7440-21-3		0.00004283	g	6299	0.6299		1799	0.1799
Copper Lead Frame		Metals	Magnesium, metal	7439-95-4		0.00000996	g	1464	0.1464		418	0.0418
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.00040144	g	59036	5.9036		16867	1.6867
Copper Lead Frame		Metals	Palladium, metal	7440-05-3		0.00000398	g	586	0.0586		167	0.0167
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0	g	0	0		0	0
Non-conductive Epoxy	0.0007						g					
Non-conductive Epoxy		Solvents, additives, and other materials	Bisphenol A	80-05-7		0.00000042	g	600	0.06		17	0.0017
Non-conductive Epoxy		Plastics/polymers	4,4'-Isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6		0.00006958	g	99400	9.94		2923	0.2923
Non-conductive Epoxy		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.00007	g	100000	10		2941	0.2941
Non-conductive Epoxy		Glass	Silicon dioxide	7631-86-9		0.00042	g	600000	60		17647	1.7647
Non-conductive Epoxy		Plastics/polymers	Proprietary Material-Other chlorinated epoxy resins	-		0.00007	g	100000	10		2941	0.2941
Non-conductive Epoxy		Plastics/polymers	Cycloaliphatic Epoxy Resin	244772-00-7		0.00007	g	100000	10		2941	0.2941
Pb Glass Frit Semiconductor Di	0.0026				7c-I		g					
Pb Glass Frit Semiconductor Di		Lead/Lead Compounds	Lead (II) titanate	12060-00-3		0.00002699	g	10381	1.0381		1134	0.1134
Pb Glass Frit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3		0.00002585	g	9943	0.9943		1086	0.1086
Pb Glass Frit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4		0.00002585	g	9943	0.9943		1086	0.1086
Pb Glass Frit Semiconductor Di		Glass	Silicon, doped	-		0.00252131	g	969733	96.9733		105937	10.5937

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/FXLN8361QR1_IPC1752_v11.xml

http://www.freescale.com/mcds/FXLN8361QR1_IPC1752A.xml